

7 A, 1200 V very fast IGBT with ultrafast diode

## Features

- High voltage capability
- High speed
- Very soft ultrafast recovery anti-parallel diode

## Applications

- Home appliance
- Lighting

## Description

This high voltage and very fast IGBT shows an excellent trade-off between low conduction losses and fast switching performance. It is designed in PowerMESH™ technology combined with high voltage ultrafast diode.

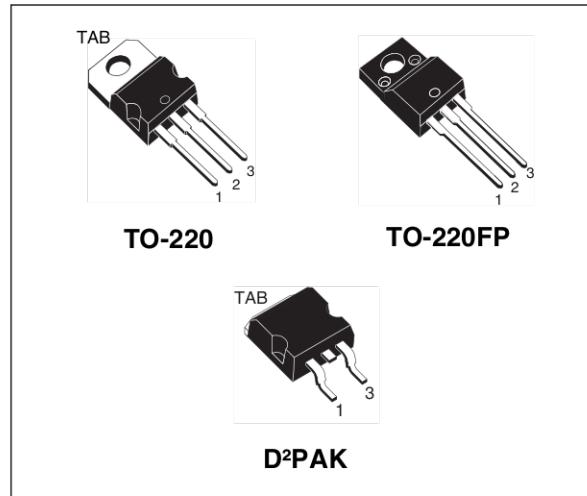


Figure 1. Internal schematic diagram

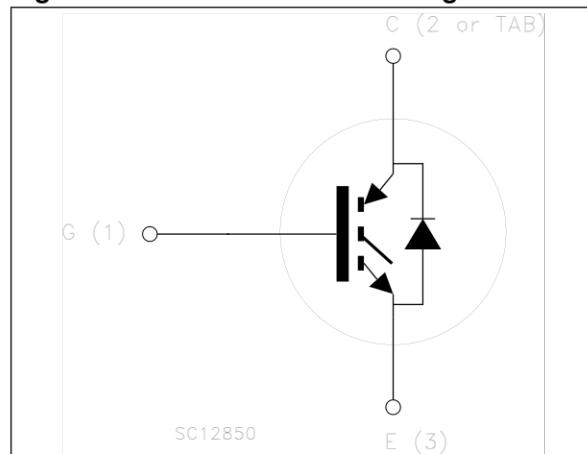


Table 1. Device summary

Order codes	Marking	Packages	Packaging
STGB3NC120HDT4	GB3NC120HD	D²PAK	Tape and reel
STGF3NC120HD	GF3NC120HD	TO-220FP	Tube
STGP3NC120HD	GP3NC120HD	TO-220	Tube

## Contents

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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value		Unit
		TO-220FP	TO-220/D <sup>2</sup> PAK	
$V_{CES}$	Collector-emitter voltage ( $V_{GE} = 0$ )	1200		V
$I_C^{(1)}$	Continuous collector current at $T_C = 25^\circ\text{C}$	6	14	A
$I_C^{(1)}$	Continuous collector current at $T_C = 100^\circ\text{C}$	3	7	A
$I_{CL}^{(2)}$	Turn-off latching current		14	A
$I_{CP}^{(3)}$	Pulsed collector current		20	A
$V_{GE}$	Gate-emitter voltage		$\pm 20$	V
$I_F$	Diode RMS forward current at $T_C = 25^\circ\text{C}$	3		A
$I_{FSM}$	Surge non repetitive forward current $t_p=10 \text{ ms sinusoidal}$		12	A
$P_{TOT}$	Total dissipation at $T_C = 25^\circ\text{C}$	25	75	W
$V_{ISO}$	Insulation withstand voltage (RMS) from all three leads to external heat sink	2500		V
$T_J$	Operating junction temperature	-55 to 150		°C

1. Calculated according to the iterative formula:

$$I_C(T_C) = \frac{T_{j(\max)} - T_C}{R_{thj-c} \times V_{CE(sat)(\max)}(T_{j(\max)}, I_C(T_C))}$$

2.  $V_{clamp} = 80\% V_{CES}$ ,  $T_j = 150^\circ\text{C}$ ,  $R_G = 10 \Omega$ ,  $V_{GE} = 15 \text{ V}$
3. Pulse width limited by maximum junction temperature and turn-off within RBSOA

**Table 3. Thermal data**

Symbol	Parameter	Value		Unit
		TO-220FP	TO-220/D <sup>2</sup> PAK	
$R_{thJC}$	Thermal resistance junction-case IGBT	5	1.65	°C/W
	Thermal resistance junction-case (diode)		3.5	°C/W
$R_{thJA}$	Thermal resistance junction-ambient		62.5	°C/W

## 2 Electrical characteristics

$T_J = 25^\circ\text{C}$  unless otherwise specified.

**Table 4. Static electrical characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{CES}}$	Collector-emitter breakdown voltage ( $V_{\text{GE}} = 0$ )	$I_C = 1 \text{ mA}$	1200			V
$V_{\text{CE}(\text{sat})}$	Collector-emitter saturation voltage	$V_{\text{GE}} = 15 \text{ V}, I_C = 3 \text{ A}$ $V_{\text{GE}} = 15 \text{ V}, I_C = 3 \text{ A}, T_J = 125^\circ\text{C}$		2.3 2.2	2.8	V V
$V_{\text{GE}(\text{th})}$	Gate threshold voltage	$V_{\text{CE}} = V_{\text{GE}}, I_C = 250\mu\text{A}$	2		5	V
$I_{\text{CES}}$	Collector cut-off current ( $V_{\text{GE}} = 0$ )	$V_{\text{CE}} = 1200 \text{ V}$ $V_{\text{CE}} = 1200 \text{ V}, T_J = 125^\circ\text{C}$			50 1	$\mu\text{A}$ mA
$I_{\text{GES}}$	Gate-emitter leakage current ( $V_{\text{CE}} = 0$ )	$V_{\text{GE}} = \pm 20 \text{ V}$			$\pm 100$	nA
$g_{\text{fs}}^{(1)}$	Forward transconductance	$V_{\text{CE}} = 25 \text{ V}, I_C = 3 \text{ A}$		4		S

1. Pulse duration: 300  $\mu\text{s}$ , duty cycle 1.5%

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{\text{ies}}$	Input capacitance			470		pF
$C_{\text{oes}}$	Output capacitance		-	45	-	pF
$C_{\text{res}}$	Reverse transfer capacitance	$V_{\text{CE}} = 25 \text{ V}, f = 1 \text{ MHz}, V_{\text{GE}} = 0$		6		pF
$Q_g$	Total gate charge			24		nC
$Q_{\text{ge}}$	Gate-emitter charge		-	3	-	nC
$Q_{\text{gc}}$	Gate-collector charge	$V_{\text{CE}} = 960 \text{ V}, I_C = 3 \text{ A}, V_{\text{GE}} = 15 \text{ V}$		10		nC

**Table 6. Switching on/off (inductive load)**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ $t_r$ ( $di/dt$ ) <sub>on</sub>	Turn-on delay time Current rise time Turn-on current slope	$V_{CC} = 800 \text{ V}$ , $I_C = 3 \text{ A}$ $R_G = 10 \Omega$ , $V_{GE} = 15 \text{ V}$ , (see Figure 20)	-	15 3.5 880	-	ns ns A/ $\mu\text{s}$
$t_{d(on)}$ $t_r$ ( $di/dt$ ) <sub>on</sub>	Turn-on delay time Current rise time Turn-on current slope	$V_{CC} = 800 \text{ V}$ , $I_C = 3 \text{ A}$ $R_G = 10 \Omega$ , $V_{GE} = 15 \text{ V}$ , $T_J = 125^\circ\text{C}$ (see Figure 20)	-	14.5 4 770	-	ns ns A/ $\mu\text{s}$
$t_r(V_{off})$ $t_d(off)$ $t_f$	Off voltage rise time Turn-off delay time Current fall time	$V_{CC} = 800 \text{ V}$ , $I_C = 3 \text{ A}$ $R_G = 10 \Omega$ , $V_{GE} = 15 \text{ V}$ , (see Figure 20)	-	72 118 250	-	ns ns ns
$t_r(V_{off})$ $t_d(off)$ $t_f$	Off voltage rise time Turn-off delay time Current fall time	$V_{CC} = 800 \text{ V}$ , $I_C = 3 \text{ A}$ $R_G = 10 \Omega$ , $V_{GE} = 15 \text{ V}$ , $T_J = 125^\circ\text{C}$ (see Figure 20)	-	132 210 470	-	ns ns ns

**Table 7. Switching energy (inductive load)**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$E_{on}^{(1)}$ $E_{off}^{(2)}$ $E_{ts}$	Turn-on switching losses Turn-off switching losses Total switching losses	$V_{CC} = 800 \text{ V}$ , $I_C = 3 \text{ A}$ $R_G = 10 \Omega$ , $V_{GE} = 15 \text{ V}$ , (see Figure 20)	-	236 290 526	-	$\mu\text{J}$ $\mu\text{J}$ $\mu\text{J}$
$E_{on}^{(1)}$ $E_{off}^{(2)}$ $E_{ts}$	Turn-on switching losses Turn-off switching losses Total switching losses	$V_{CC} = 800 \text{ V}$ , $I_C = 3 \text{ A}$ $R_G = 10 \Omega$ , $V_{GE} = 15 \text{ V}$ , $T_J = 125^\circ\text{C}$ (see Figure 20)	-	360 620 980	-	$\mu\text{J}$ $\mu\text{J}$ $\mu\text{J}$

1.  $E_{on}$  is the turn-on losses when a typical diode is used in the test circuit in figure 2. If the IGBT is offered in a package with a co-pack diode, the co-pack diode is used as external diode. IGBTs & Diode are at the same temperature ( $25^\circ\text{C}$  and  $125^\circ\text{C}$ )
2. Turn-off losses include also the tail of the collector current

**Table 8. Collector-emitter diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_F$	Forward on-voltage	$I_F = 1.5 \text{ A}$ $I_F = 1.5 \text{ A}$ , $T_J = 125^\circ\text{C}$	-	1.6 1.3	2.0	V
$t_{rr}$ $Q_{rr}$ $I_{rrm}$	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_F = 3 \text{ A}$ , $V_R = 40 \text{ V}$ , $di/dt = 100 \text{ A}/\mu\text{s}$ (see Figure 23)	-	51 85 3.3	-	ns nC A
$t_{rr}$ $Q_{rr}$ $I_{rrm}$	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_F = 3 \text{ A}$ , $V_R = 40 \text{ V}$ , $T_J = 125^\circ\text{C}$ , $di/dt = 100 \text{ A}/\mu\text{s}$ (see Figure 23)	-	64 133 4.2	-	ns nC A

## 2.1 Electrical characteristics (curves)

Figure 2. Output characteristics

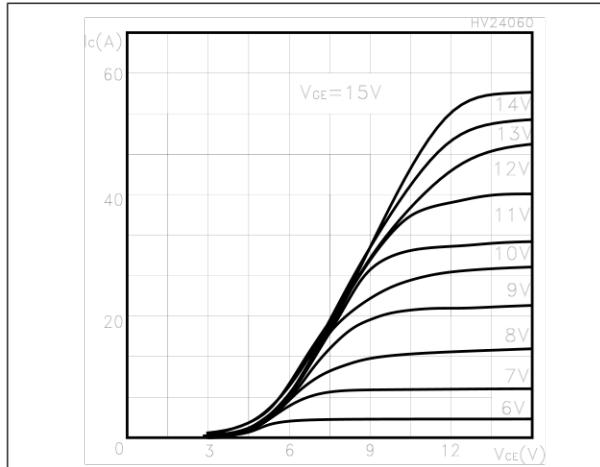


Figure 3. Transfer characteristics

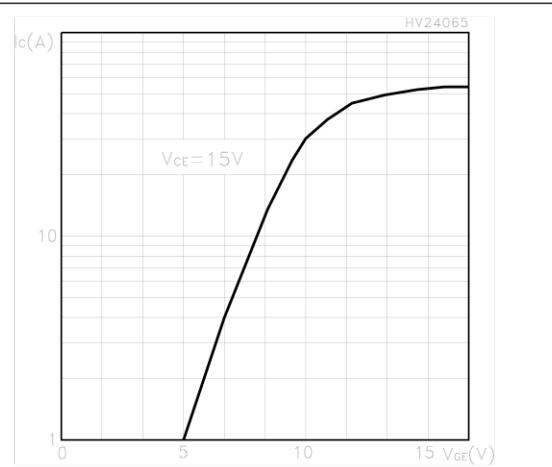


Figure 4. Transconductance

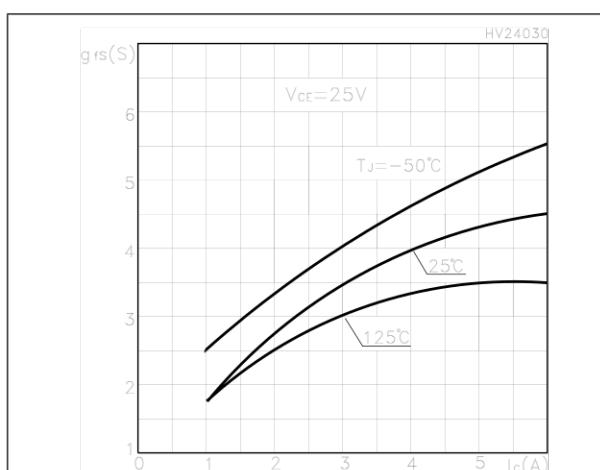


Figure 5. Collector-emitter on voltage vs. temperature

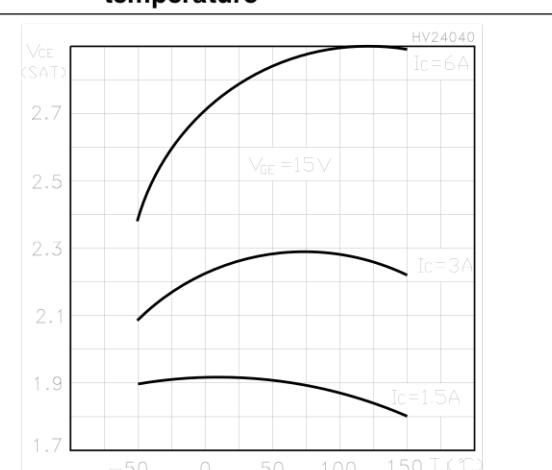


Figure 6. Collector-emitter on voltage vs. collector current

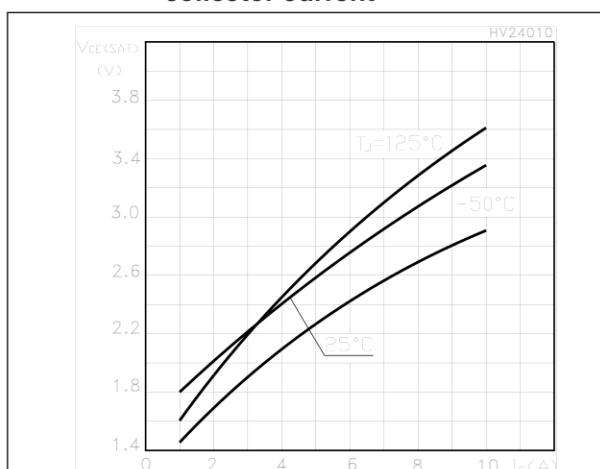
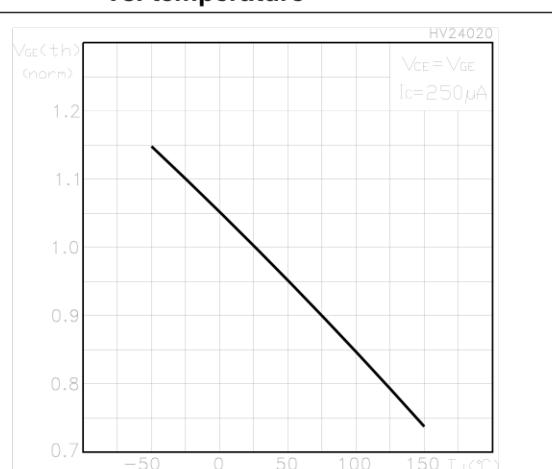
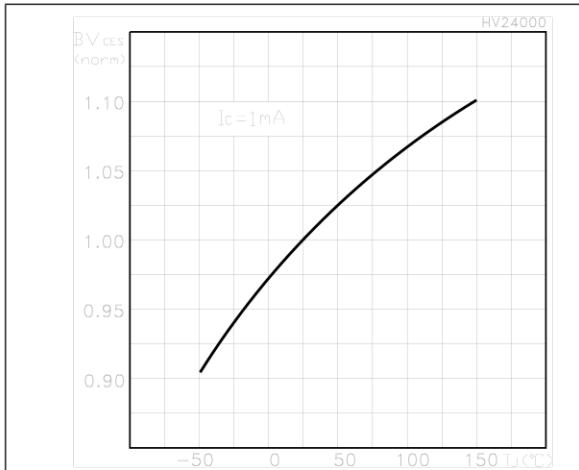
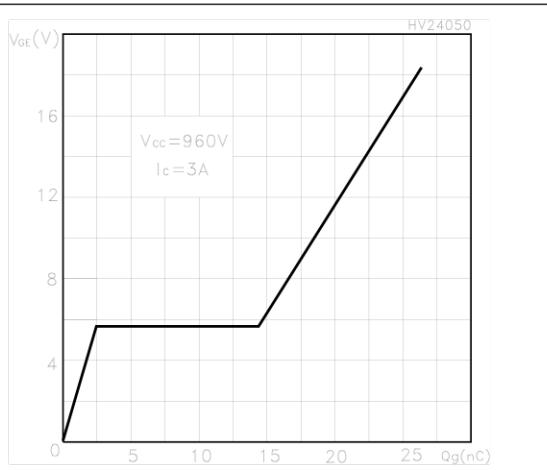
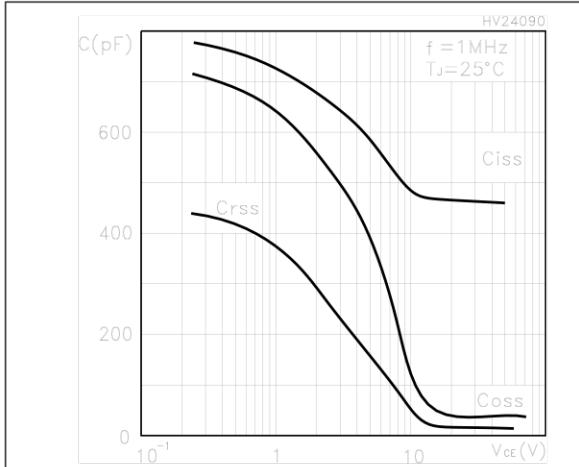
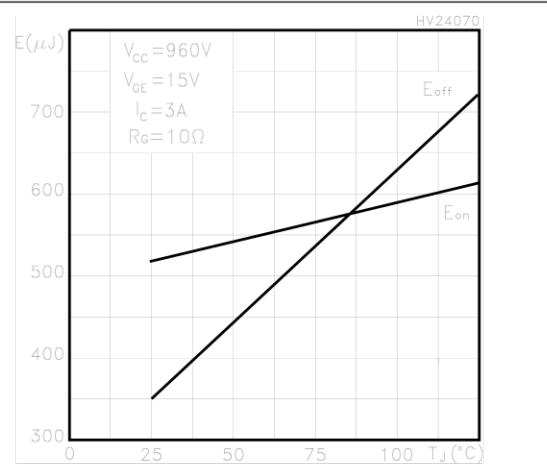
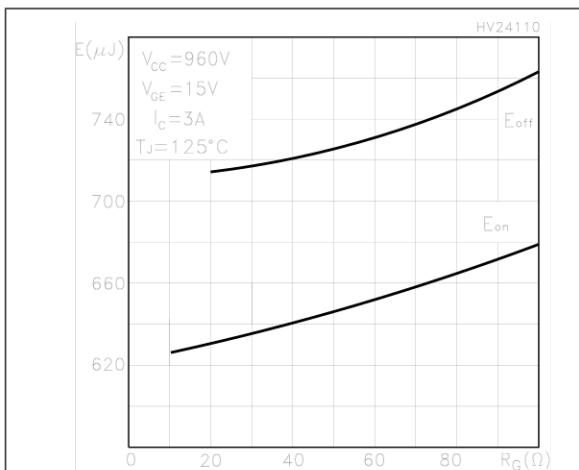
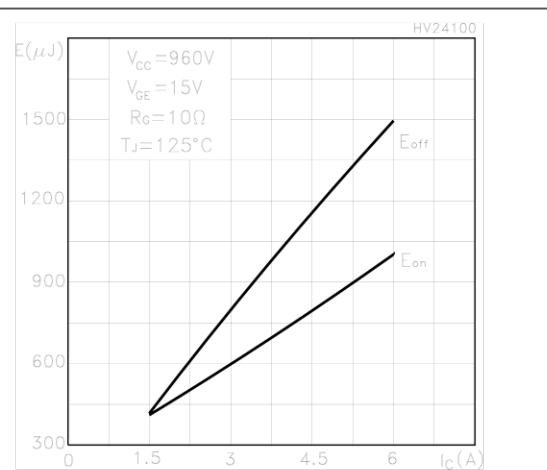
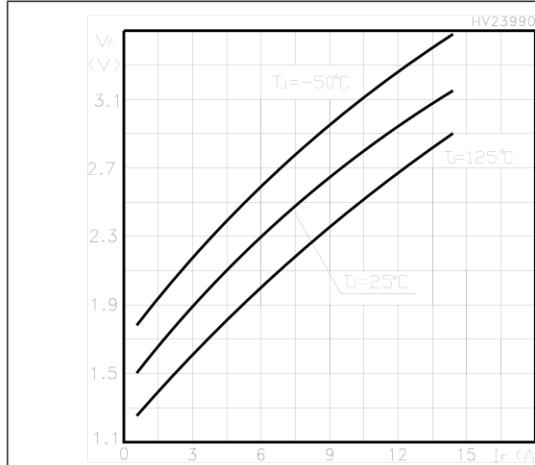


Figure 7. Normalized gate threshold voltage vs. temperature

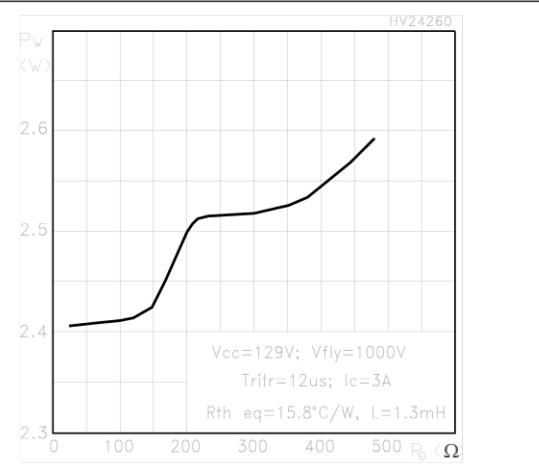


**Figure 8.** Normalized breakdown voltage vs. temperature**Figure 9.** Gate charge vs. gate-source voltage**Figure 10.** Capacitance variations**Figure 11.** Switching losses vs. temperature**Figure 12.** Switching losses vs. gate resistance**Figure 13.** Switching losses vs. collector current

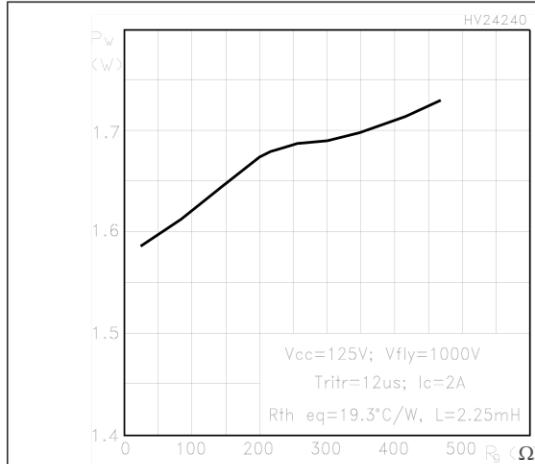
**Figure 14. Collector-emitter diode characteristics**



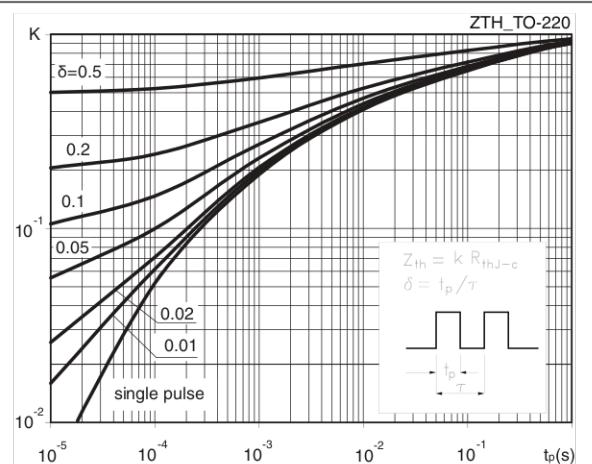
**Figure 15. Power losses @  $I_C = 3 \text{ A}$**



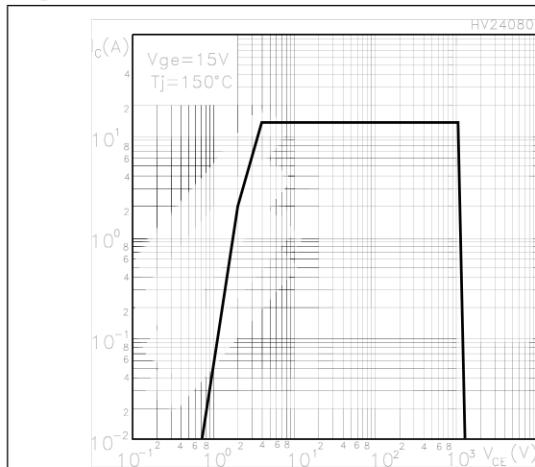
**Figure 16. Power losses @  $I_C = 2 \text{ A}$**



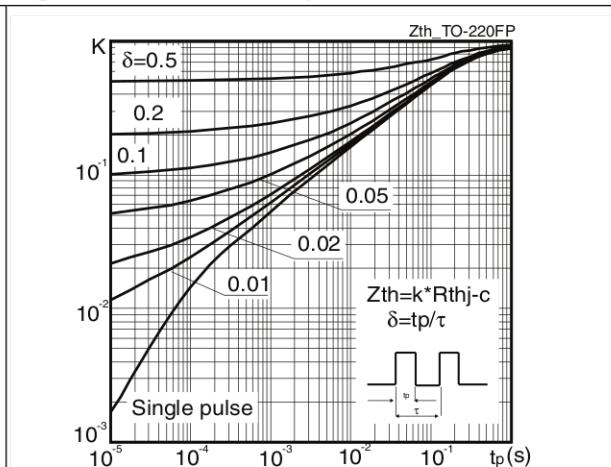
**Figure 17. Thermal impedance for TO-220**



**Figure 18. Turn-off SOA**

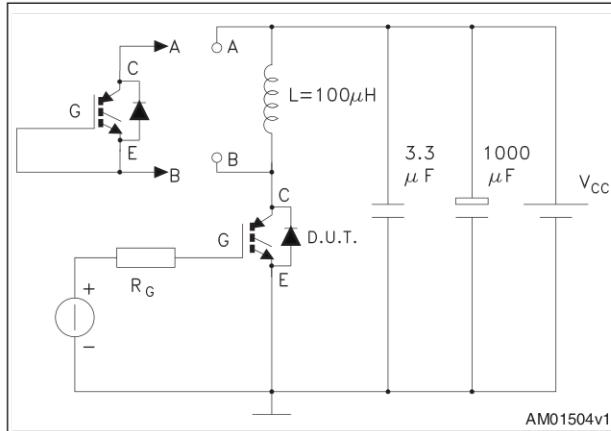


**Figure 19. Thermal impedance for TO-220FP**

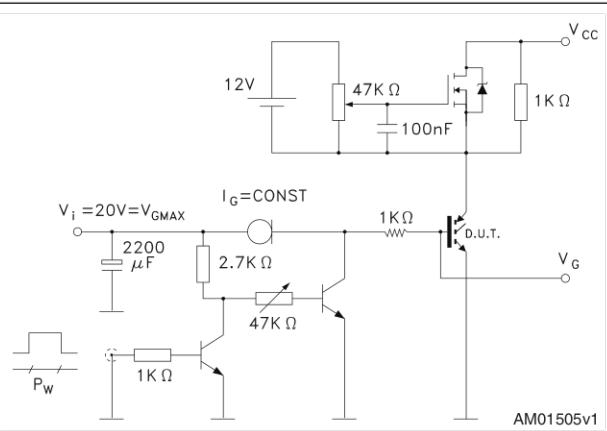


### 3 Test circuit

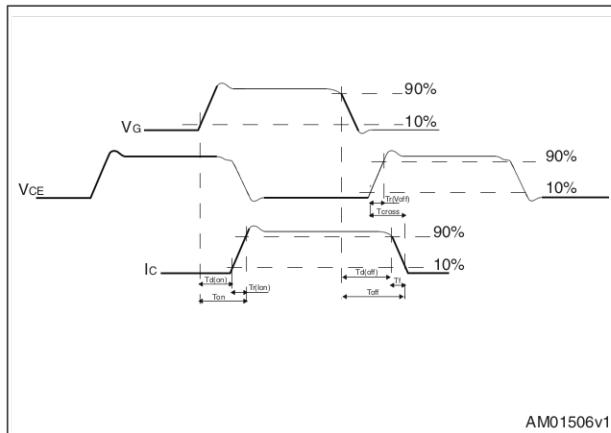
**Figure 20. Test circuit for inductive load switching**



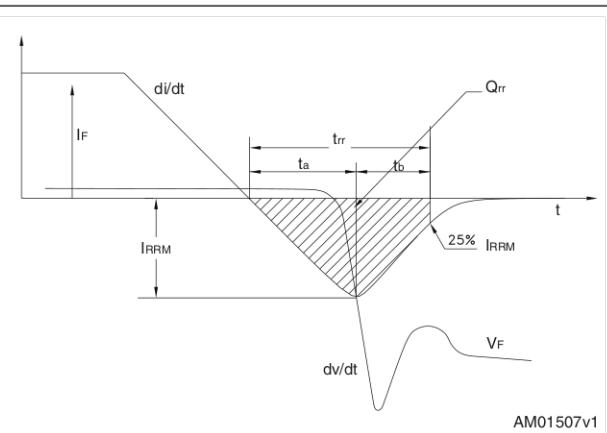
**Figure 21. Gate charge test circuit**



**Figure 22. Switching waveform**



**Figure 23. Diode recovery time waveform**

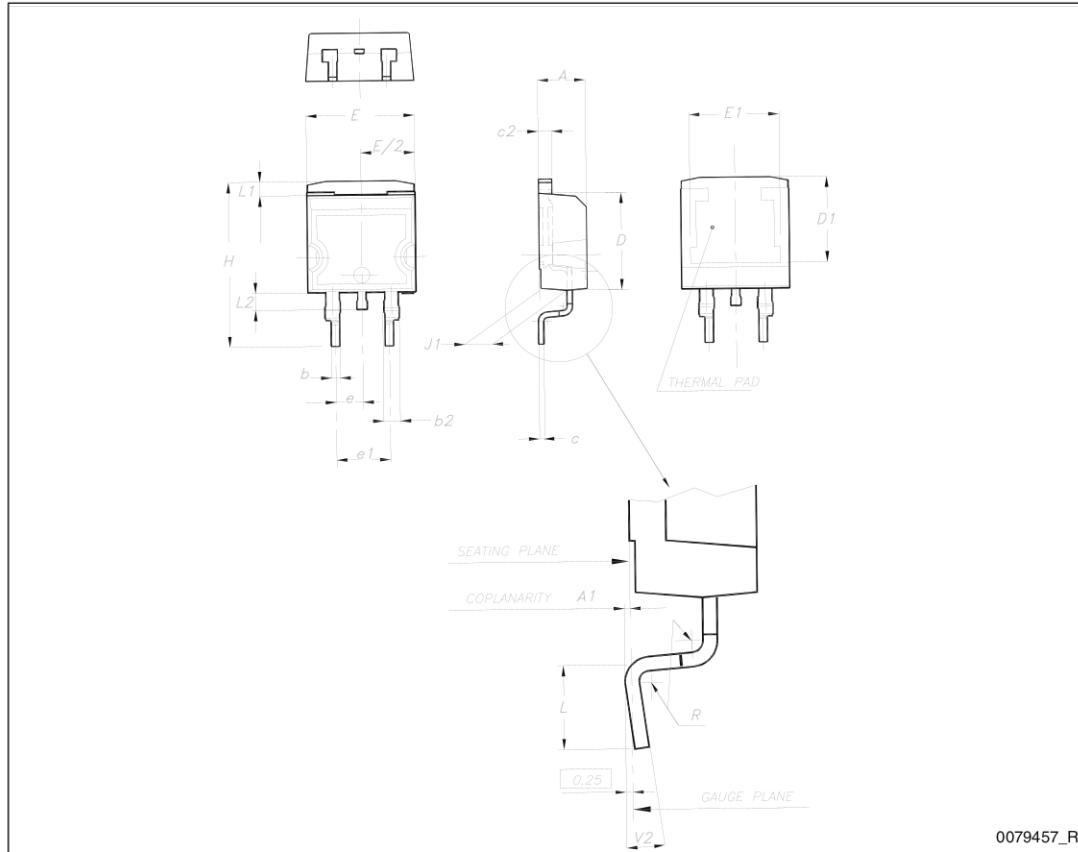


## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

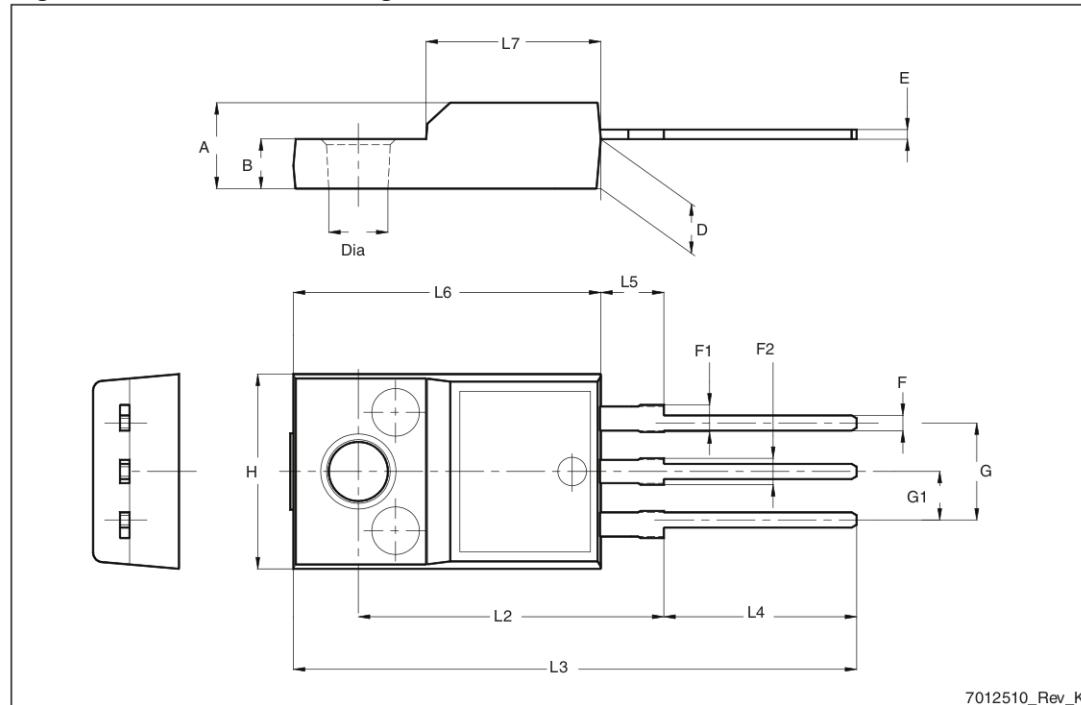
**Table 9. D<sup>2</sup>PAK (TO-263) mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50		
E	10		10.40
E1	8.50		
e		2.54	
e1	4.88		5.28
H	15		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.4	
V2	0°		8°

D<sup>2</sup>PAK (TO-263) drawing

**Table 10.** TO-220FP mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.6
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
H	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

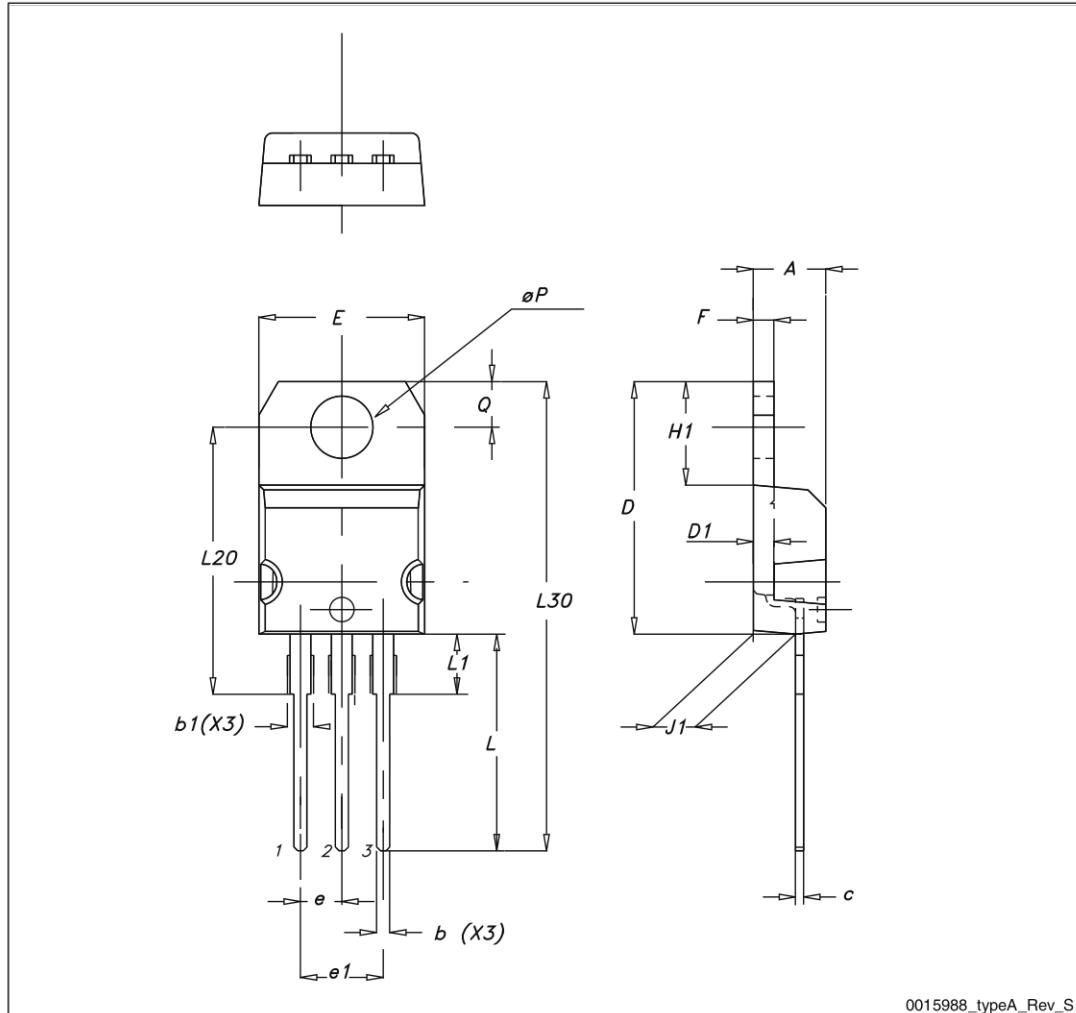
**Figure 24.** TO-220FP drawing

7012510\_Rev\_K

**Table 11.** TO-220 type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
ØP	3.75		3.85
Q	2.65		2.95

## TO-220 type A drawing



## 5 Revision history

**Table 12. Document revision history**

Date	Revision	Changes
13-Dec-2004	1	First release.
21-Jan-2005	2	Modified <a href="#">Figure 18: Turn-off SOA</a> .
03-May-2010	3	Added new package, mechanical data: TO-220.
25-Jan-2011	4	Added new package, mechanical data: D <sup>2</sup> PAK.

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